

## **Technical Data Sheet**

### MODEL NO: Q150Y4-INH

3216 Package 3.2\*1.6mm Chip LED

Features:

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

•Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP	Yellow	Water clear

## Electrical/Optical Characteristics(Ta=25°C)

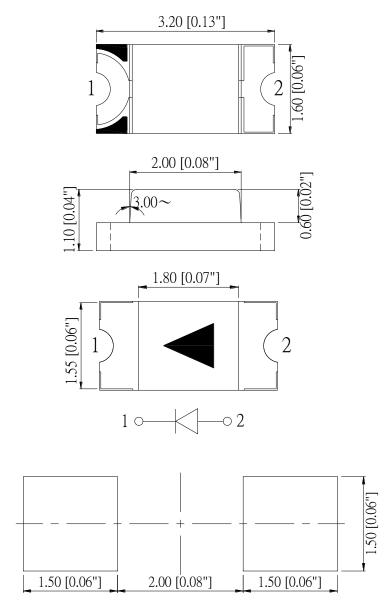
Parameter	Test Condition	Value			llait	
		Symbol	Min	Тур	Мах	Unit
Dominant wavelength	l⊧=20mA	λd	584		594	nm
Spectral half bandwidth	l⊧=20mA	Δλ		17		nm
Forward voltage	l⊧=20mA	VF	1.8		2.4	V
Luminous intensity	l⊧=20mA	lv	80	130		mcd
Viewing angle at 50% lv	l⊧=10mA	20 1/2		120		Deg
Reverse current	Vr=5V	lr			10	μΑ

### Absolute Maximum Ratings(Ta= $25^{\circ}C$ )

Parameter	Symbol	Value	Unit
Power dissipation	Pd	72	mW
Forward current	lF	30	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	İFP	125	mA
120CT15D			•



## PACKAGING DIMENSIONS (mm):



## **Precautions For Use :**

### **Over - current - proof**

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

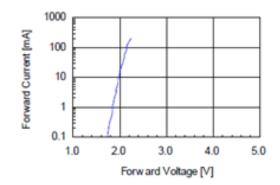
### Storage

1. The operation of temperature and R.H. are :  $5^{\circ}$ C ~  $30^{\circ}$ C ,  $60^{\circ}_{0}$ R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}C\pm 5^{\circ}C$  for 15hrs.



## Typical Electro-Optical Characteristic Curves



#### Fig 1. Forward Current vs. Forward Voltage



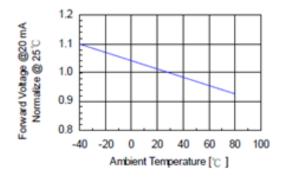


Fig 5. Relative Intensity vs. Wavelength

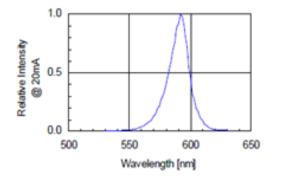


Fig 2. Relative Intensity vs. Forward Current

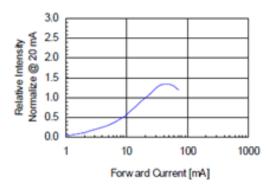
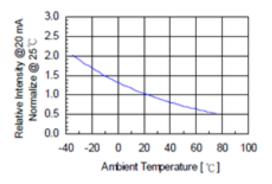
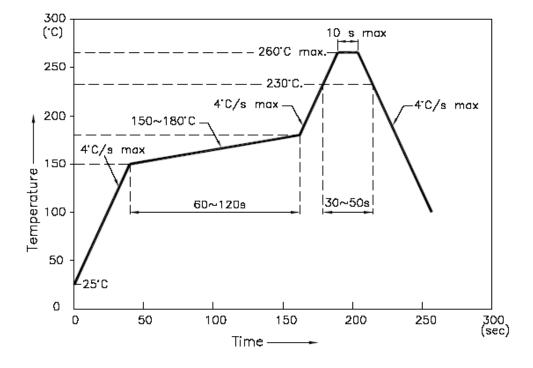


Fig 4. Relative Intensity vs. Temperature





## ■ Reflow Temp/Time



### NOTES:

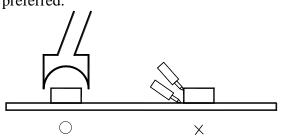
- 1. We recommend the reflow temperature  $245^{\circ}C(\pm 5^{\circ}C)$ .the maximum soldering temperature should be limited to  $260^{\circ}C$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

#### ■Soldering iron

Basic spec is  $\leq 5$  sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

### Rework

- 1. Customer must finish rework within 5 sec under  $260^{\circ}$ C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.

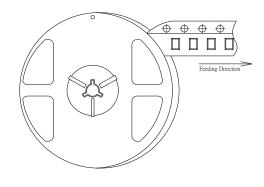


■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.



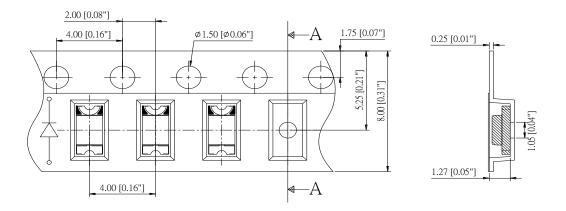
## **Packaging Specifications**

• Feeding Direction



• Dimensions of Reel (Unit: mm)

• Dimensions of Tape (Unit: mm)



• Arrangement of Tape

